



SOT78C

plastic single-ended package; heatsink mounted; 1 mounting hole; 3-leads

8 February 2016

Package information

1. Package summary

Terminal position code	S (single)
Package type descriptive code	TO-220AB
Package type industry code	TO-220AB
Package style descriptive code	SFM (single-ended flange mount)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
Mounting method type	H (heatsink mount)
Issue date	28-11-2012

Table 1. Package summary

Symbol	Parameter		Min	Typ	Nom	Max	Unit
D	package length		14.8	-	14.95	15.07	mm
E	package width		10	-	10.2	10.4	mm
A	seated height		4.31	-	4.45	4.58	mm
A ₂	package height		0.05	-	0.1	0.15	mm
e	nominal pitch		-	-	2.54	-	mm
n ₂	actual quantity of termination		-	-	3	-	



2. Package outline

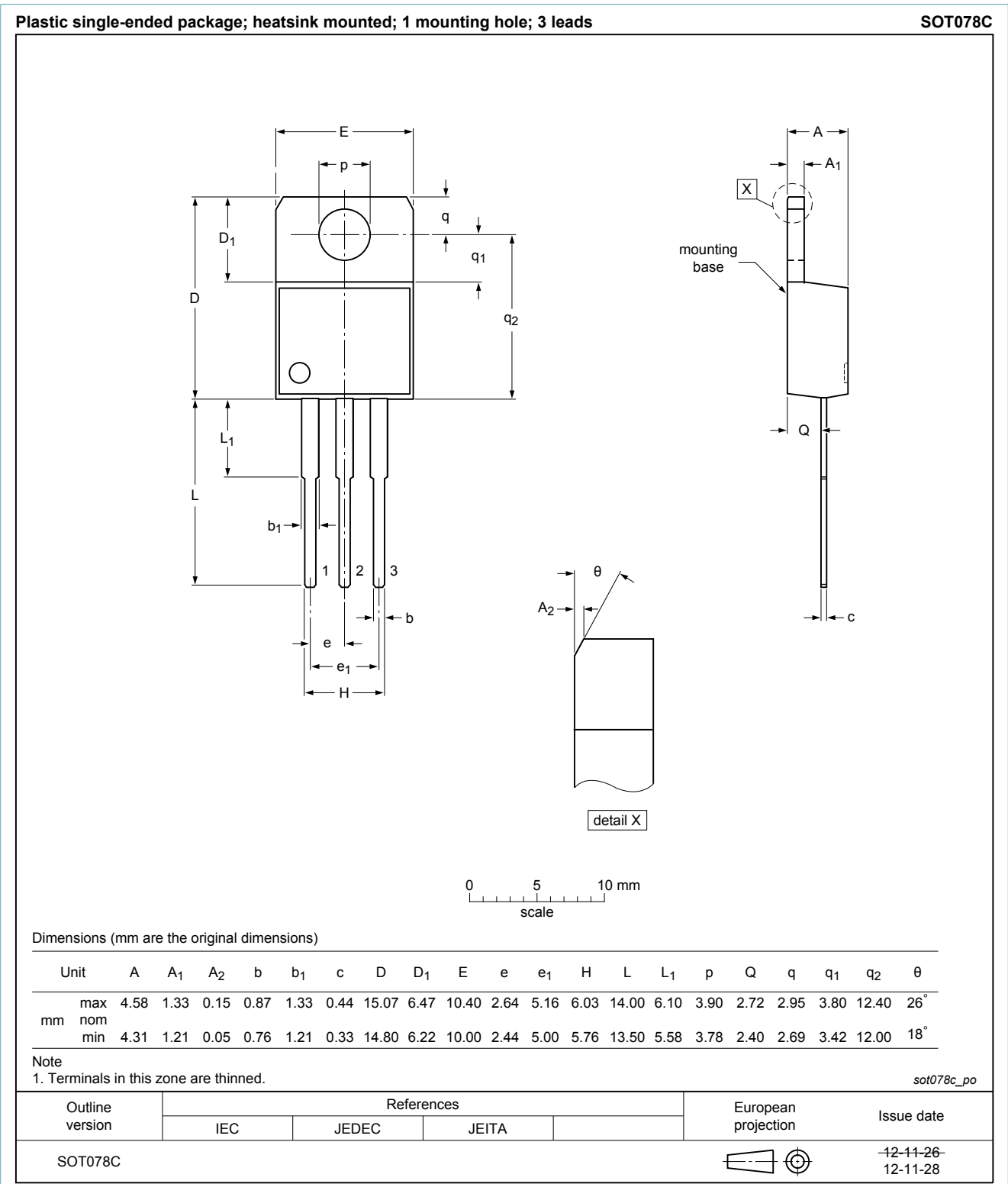


Fig. 1. Package outline TO-220AB (SOT78C)

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3. Soldering

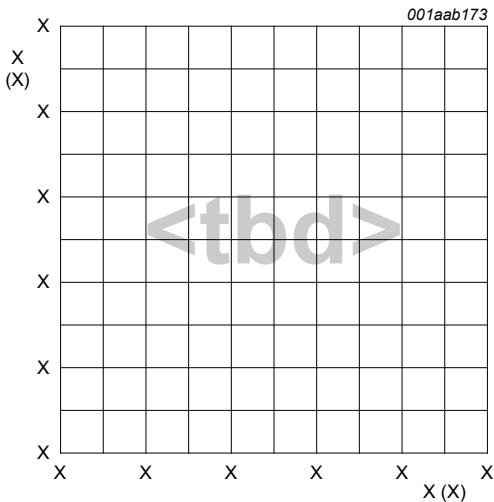


Fig. 2. Reflow soldering footprint for TO-220AB (SOT78C)

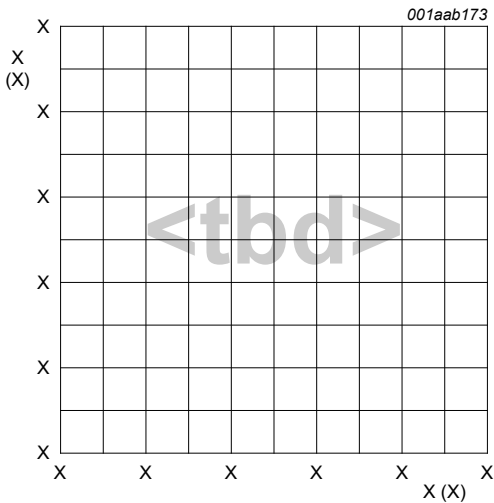


Fig. 3. Wave soldering footprint for TO-220AB (SOT78C)

4. Legal information

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